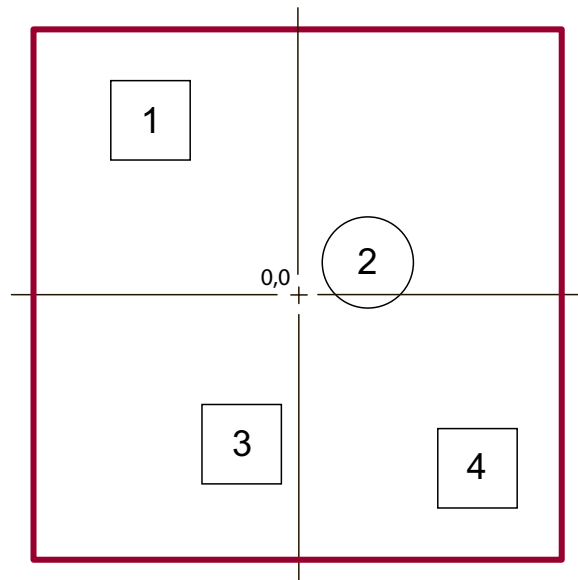


**Pad Layout**



**Die Specifications**

Die Dimensions (mils)			Die Dimensions (µm)			Back Side Metal	Back Side	Bonding Pad Material
Length <sup>1</sup>	Width <sup>1</sup>	Thickness	Length <sup>1</sup>	Width <sup>1</sup>	Thickness			
29.92	29.92	9.49 - 12.52	760	760	241 - 318	None	Source Voltage	Al/Cu/Si

**Pad Descriptions**

Pad #	Function	x Position <sup>2</sup> (µm)	y Position <sup>2</sup> (µm)	x Size (µm)	y Size (µm)
1	Gate	-196	246.95	100	99.9
2	Drain	97	52	108	108
3	Source	-75	-207.05	100	98.9
4	No Connect <sup>3</sup>	250	-238.05	100	98.9

**Notes:**

1. Maximum values.
2. Position referenced to center of pad.
3. Do not connect.

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